

# H140A

## 特性/Features

Tg:135±5°C (DSC)

UV Blocking与 AOI兼容可提高PCB生产效率

UV Blocking and AOI compatible, so as to increase productivity efficiency

可依需求提供不具UV阻挡功能的自然色板材（白料）  
No UV Blocking and natural color CCL upon request

可依需求提供介电常数为：

4.3±0.3 (1 MHz)的FR-4板材

According to necessity to provide a dielectric constant:

4.3 ± 0.3 (1 MHz) of FR-4 plate

## 应用领域/Applications

适合于2-6层PCB、计算机及外围设备、通讯设备、办公自动设备等。

Suitable for medium multilayer printed circuit board, computer, communication equipment, OA equipment, etc.

## 主要特性/General properties

检测项目 Item	单位 Unit	检测条件 Test Condition	规范值 Spec	典型值 Typical Value
玻璃化转变温度/Tg	°C	DSC	135±5	135.5
剥离强度/1oz Peel Strength	N/mm	288°C, 10S	≥1.40	1.81
热应力/Thermal stress	S	288°C,solder dip	> 10	120 s No delamination
弯曲强度/Flexural Strength	N/mm <sup>2</sup>	经向 LW 纬向 CW	≥415 ≥345	580 485
燃烧性/Flammability	—	E 24/125	UL94V-0	V-0
表面电阻/Surface Resistivity	MΩ	After moisture	≥1.0×10 <sup>4</sup>	5.16×10 <sup>7</sup>
体积电阻/Volume Resistivity	MΩ·cm	After moisture	≥1.0×10 <sup>6</sup>	5.07×10 <sup>8</sup>
介电常数/Dielectric Constant	—	1 MHz C 24/23/50	≤5.4	4.8
介质损耗角正切/Loss Tangent	—	1 MHz C 24/23/50	≤0.035	0.015
耐电弧/Arc Resistance	S	D48/50+D0.5/23	≥60	125
击穿电压/Dielectric Breakdown	KV	D48/50+D0.5/23	≥40	58
吸水率/Moisture Absorption	%	D24/23	≤0.35	0.15
热分解温度/Td	°C	Weight Loss 5%	—	310
CTE Z-axis	Alpha 1	ppm / °C	—	60
	Alpha 2	ppm / °C	TMA	300
	50 - 260 °C	%	—	4.3
T288	min	TMA	—	2
相比漏电起痕指数/CTI	V	IEC-60112	175~250	200

Specimen Thickness: 1.6mm; Specification Sheet: IPC-4101D/21, 97, is for your reference only

Explanation: C: Humidity conditioning; D: Immersion conditioning in distilled water;

E: Temperature conditioning;

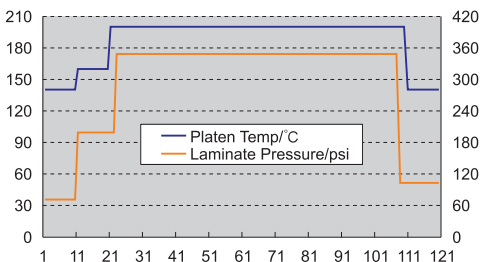
# 半固化片介绍-H140AP

## Prepreg instruction

H140AP(UV Prepreg):

Prepreg Type	Resin Content(%)		压合厚度 / Cured Thickness			
	含量R/C(%)	公差Tolerance	Nominal		Range(±)mil	
	%	±	mm	mil	mm	mil
7628HRC	52	2	0.247	9.71	0.024	0.95
	50	2	0.234	9.23	0.023	0.9
	48	2	0.224	8.83	0.023	0.9
7628	45	2	0.207	8.15	0.020	0.8
	43	2	0.197	7.76	0.020	0.8
1506	48	2	0.175	6.89	0.018	0.7
	45	2	0.163	6.42	0.017	0.65
	43	2	0.155	6.1	0.015	0.6
2116	58	2	0.145	5.71	0.015	0.6
	57	2	0.142	5.59	0.014	0.55
	55	2	0.134	5.28	0.014	0.55
	53	2	0.127	5.00	0.013	0.5
	50	2	0.119	4.69	0.013	0.5
1080	68	2	0.093	3.66	0.010	0.4
	65	2	0.082	3.23	0.008	0.3
	63	2	0.078	3.07	0.008	0.3
	60	2	0.073	2.87	0.008	0.3

建议压制程式：Suggest cycle



Heat-up rate:1.0~2.5°C/min(80~140°C)

Curing time:>30min(>170°C)

The hot pressing parameters is for your reference only, please turn to Zhejiang Huazheng New Material .Co.,Ltd for detailed information.

储存条件：

温度≤23°C、湿度≤50%，保存时间3个月；  
温度≤5°C、密封条件下，保存时间6个月。

Storage Condition:

T≤23°C & ≤50%RH, Within 3 months;  
T≤5°C Within 6 months (seal condition)

在上述要求内，我司可立即安排PP送样；  
若有特殊要求，由供需双方商定。

Follow above condition, our company will arrange sample immediately. We can discuss if you have any special requirement.